

TCAS-AI Journal Status

- During the Nov. IEEE TAB meeting (11/15-11/18), CASS, SSCS and CEDA presidents/president-elects reached an agreement on the following terms:
 - Financial sponsorship shares: CASS 57%, SSCS 15% and CEDA 28%
 - Management committee: CASS 3 members, CSCC 1 member, CEDA 2 members with a chair position appointed by CASS
 - No change in the journal title “TCASAI” (Transactions on Circuits and Systems for Artificial Intelligence)
- Timeline:
 - 12/15/2023: CASS will submit Phase 2 form to IEEE at periodical@ieee.org
 - 12/30/2023: Phase 2 form will be sent and reviewed to Periodical Committee members
 - 01/2024: FinCom Publication Ad-Hoc Budget Review & FinCom Decision
 - 02/2024: TAB Decision
 - 02/2024: If approved, Signed financial MOU and Technical MOU submitted to periodical@ieee.org
- Special thanks go to Enrico & Georges for preparing options with Gianluca from CASS promptly before the TAB meeting.

IEEE DiscoveryPoint Targeting Semiconductor Industry Segments

Our intention is that IDPS will address the information needs of practicing engineers in all parts of the global semiconductors industry

We recognize 7 operational segments. Each industry segment feeds its resources up the value chain until finally a chip factory (a “Fab”) has all the designs, equipment, and materials necessary to manufacture a chip.

1. **Electronic Design Automation (EDA) Tools and Intellectual Property (IP) Cores** – e.g. *Cadence, Mentor, Synopsys, ARM*
2. **Specialized Materials** – e.g. *Air Liquide, Dow Chemical*
3. **Wafer Fab Equipment (WFE)** – e.g. *ASML, AMAT, Tokyo Electron, KLA, LAM*
4. **“Fabless” Chip Companies** – e.g.. *Qualcomm, NVIDIA, Xilinx*
5. **Integrated Device Manufacturers (IDMs)**
*There are 3 categories of IDMs– **Memory** (e.g.. Micron, SK Hynix), **Logic** (e.g.. Intel), **Analog** (e.g. TI, Analog Devices)*
6. **Chip Foundries** – e.g. *TSMC, GlobalFoundries, Samsung*
7. **Outsourced Semiconductor Assembly and Test (OSAT)** – e.g., *Amkor*

PHIL KAUFMAN AWARD CEREMONY & BANQUET



JOIN US TO HONOR—



Dr. Lawrence T. Pileggi

Coraluppi Head and Tanoto
Professor of Electrical and
Computer Engineering

Carnegie Mellon University

ABOUT THE RECIPIENT

Dr. Pileggi is being recognized for his significant contributions to the Electronic System Design Industry.

ABOUT THE AWARD

The Phil Kaufman Award honors individuals who have had a demonstrable impact on the field of electronic system design through technology innovations, education/mentoring, or business or industry leadership.

MORE INFO & REGISTER HERE



<https://bit.ly/2022PK>

Please new QR code

February 22, 2024 | 6:30–9:30pm | The Glasshouse | San Jose, CA
Immediately following ISSCC on Thursday Evening

CEDA awards and position nominations

- Call for Nominations for Editor-in-Chief of the IEEE Embedded Systems Letters
 - <https://ieeeced.org/post/call-nominations-editor-chief-ieee-embedded-systems-letters-1>
 - Nomination Deadline: Nov. 20, 2023
- A. Richard Newton Technical Impact Award in Electronic Design Automation
 - <https://ieeeced.org/awards/richard-newton-technical-impact-award-electronic-design-automation>
 - Nomination Deadline: Feb 28, 2024

Follow-up Items in Dec and 2024

- Enrico Maccii to develop a document on the roadmap of the proposed initiative for young engineers' program by DATE 2024.
- Marina Zapater to adjust the student travel grant policy to include the travel expenses that are allowed.
- Tsung-Yi Ho to contact Vivek to host a joint panel at DAC.
- Amanda Osborn and Tsung-Yi Ho to touch base offline to discuss the December 11, 2023 chapter summit meeting.
- Gi-Joon Nam to reach out IWLS organizers about listing CEDA as a technical sponsor on their website.
- Amanda Osborn to send Georges and Tulika the IEEE form for establishing a new award.
- Mehdi to reach out to Nicola to organize an interview with the Kaufman Award winners for an interview to be included in the D&T Magazine.
- Gi-Joon Nam to discuss the IEEE VP Conferences the process of elevating a workshop to a symposium. (MLCAD).
- Tsung-Yi Ho to request a post-event report for ISEDA 2023 to Cristiana Bolchini.
- Gi-Joon Nam to follow-up on the SSCS request for CEDA-related contents for their newsletter.
- Gi-Joon Nam to read and review the Bylaws for the VP, Assistant VP roles and committee composition.
- Gi-Joon Nam & Miguel Silveira finalize the website upgrade plan.
- Gi-Joon Nam will contact new IEEE fellows (6), congratulate them individually and get conferences to be recognized.

CEDA Officers 2024-2025 (EC Approved)

	EC Members	Assistant VP Candidates
President	Miguel Silveira	
President-elect	Cristiana Bolchini	
Past President	Gi-Joon Nam	
Secretary	Ioana Vatajelu	Mohammad Al Faruque
Vice-President for Finances	Marina Zapater	Jiang Hu
Vice-President for Activities	Ian O'Connor	Vasilis Pavlidis
Vice-President for Awards	Tulika Mitra	Deming Chen
Vice-President for Conferences	Tsung-Yi Ho	Mehdi Tahoori
Vice-President for Initiatives	Qi Zhu	Ibrahim Elfadel
Vice-President for Publications	Joerg Henkel	Preti Panda
Vice-President for Publicity	Sri Parameswaran	Bei Yu
Vice-President for Standards	Aparna Dey (Cadence)	Dennis Brophy
Vice-President for Strategy	Georges Gielen	Subhasish Mitra
Young Professionals Coordinator	Iris Hui-Ru Jiang	Jinwook Jung

Motion: To Approve the Assistant VPs 2024-2025

- Motion: To approve the slate of the Assistant VPs 2024-2025

	Candidates
Assistant Secretary	Mohammad Al Faruque
Assistant Vice-President for Finances	Jiang Hu
Assistant Vice-President for Activities	Vasilis Pavlidis
Assistant Vice-President for Awards	Deming Chen
Assistant Vice-President for Conferences	Mehdi Tahoori Assistant
Assistant Vice-President for Initiatives	Ibrahim Elfadel
Assistant Vice-President for Publications	Preti Panda
Assistant Vice-President for Publicity	Bei Yu
Assistant Vice-President for Standards	Dennis Brophy
Assistant Vice-President for Strategy	Subhasish Mitra
Assistant Young Professionals Coordinator	Jinwook Jung

IEEE DiscoveryPoint for Communications

Delivering to engineers' information needs in industry

Why we developed IDPC

- Meet the IEEE Mission and Vision to foster innovation in engineering
- Diversify product revenue beyond academia
- Meet the information needs of non-research engineers and drive engagement with IEEE
- Develop and test a “prototype” repeatable product model to target these users reliably
- Support IEEE relevance to industry, ultimately opening up membership opportunities

What we did

- Studied workflows of practicing engineers in industry
- Built prototypes and thoroughly tested the product and its business model
- Developed a business plan to serve the mission of the IEEE, meet the needs of users, and deliver surplus to the IEEE

IEEE DiscoveryPoint for Communications

A single destination where practicing engineers can:

- Find answers to technical questions by discovering relevant content from multiple, high-quality sources
- Explore technology innovation and get up to speed quickly on new topics
- Find and use relevant content more effectively with semantic search and easy-to-navigate design
- Use AI-generated insights to pinpoint relevant documents